Abstract

Method and Device for Slicing a Multiplicity of Wafers from a Workpiece

The invention relates to a device suitable for sawing a workpiece, which comprises a wire gang formed by a sawing wire, a forward feed instrument holding the workpiece to be sawed and feeding the workpiece in the direction of the wire gang, as well as a reservoir filled with a sawing suspension, the reservoir being arranged and filled such that at least the part of the sawing wire which is in engagement during the sawing process is respectively immersed into the sawing suspension of the reservoir.

The invention also relates to a method for sawing a workpiece, in which the workpiece is fed through a wire gang formed by a sawing wire, characterized in that kerfs of the workpiece are filled with sawing suspension during the sawing process.

Fig. 1